

Features

- N-Channel, 5V Logic Level Control
- Enhancement mode
- Very low on-resistance $R_{DS(on)}$ @ $V_{GS}=4.5$ V
- Fast Switching
- 100% Avalanche Tested
- Pb-free lead plating; RoHS compliant

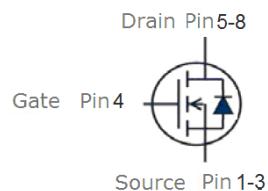


V_{DS}	40	V
$R_{DS(on),TYP}$ @ $V_{GS}=10$ V	5.5	mΩ
$R_{DS(on),TYP}$ @ $V_{GS}=4.5$ V	6.6	mΩ
I_D	62	A

PDFN5x6



Part ID	Package Type	Marking	Tape and reel information
VSP007N04MS	PDFN5x6	007N04M	3000pcs/Reel



Maximum ratings, at $T_j=25$ °C, unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	40	V
I_s	Diode continuous forward current	$T_c=25$ °C	A
I_D	Continuous drain current@ $V_{GS}=10$ V	$T_c=25$ °C	A
		$T_c=100$ °C	A
I_{DM}	Pulse drain current tested ①	$T_c=25$ °C	A
EAS	Avalanche energy, single pulsed ②	272	mJ
P_d	Maximum power dissipation	$T_c=25$ °C	W
V_{GS}	Gate-Source voltage	±20	V
$T_{STG} T_J$	Storage and operating temperature range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	3	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	48	°C/W

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	40	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	μA
	Zero Gate Voltage Drain Current($T_j=125^\circ\text{C}$)	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}$	--	--	100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.6	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=30\text{A}$	--	5.5	7.0	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=15\text{A}$	--	6.6	9.0	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	--	2370	--	pF
C_{oss}	Output Capacitance		--	275	--	pF
C_{rss}	Reverse Transfer Capacitance		--	190	--	pF
R_g	Gate Resistance	f=1MHz		3.7		Ω
Q_g	Total Gate Charge	$V_{\text{DS}}=20\text{V}, I_{\text{D}}=20\text{A}, V_{\text{GS}}=10\text{V}$	--	56	--	nC
Q_{gs}	Gate-Source Charge		--	11	--	nC
Q_{gd}	Gate-Drain Charge		--	16	--	nC
Switching Characteristics						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=20\text{V}, I_{\text{D}}=10\text{A}, R_{\text{G}}=3.5\Omega, V_{\text{GS}}=10\text{V}$	--	10	--	nS
t_r	Turn-on Rise Time		--	21	--	nS
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		--	43	--	nS
t_f	Turn-Off Fall Time		--	22	--	nS
Source- Drain Diode Characteristics@ $T_j = 25^\circ\text{C}$ (unless otherwise stated)						
V_{SD}	Forward on voltage	$I_{\text{SD}}=30\text{A}, V_{\text{GS}}=0\text{V}$	--	0.82	1.2	V
t_{rr}	Reverse Recovery Time	$T_j=25^\circ\text{C}, I_{\text{SD}}=20\text{A}, \frac{di}{dt}=500\text{A}/\mu\text{s}$	--	36	--	nS
Q_{rr}	Reverse Recovery Charge			31		nC

NOTE:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by $T_{j\text{max}}$, starting $T_j = 25^\circ\text{C}$, $L = 0.5\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 33\text{A}$, $V_{GS} = 10\text{V}$. Part not recommended for use above this value
- ③ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.



Vanguard
Semiconductor

VSP007N04MS

40V/62A N-Channel Advanced Power MOSFET

Typical Characteristics

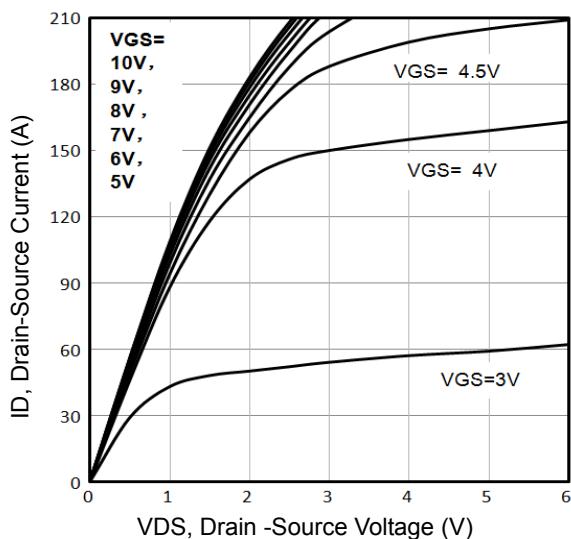


Fig1. Typical Output Characteristics

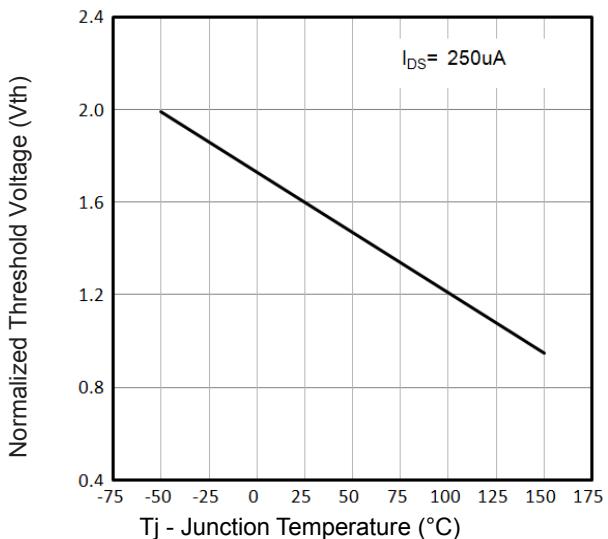


Fig2. $V_{GS(TH)}$ Gate-Source Voltage Vs. T_j

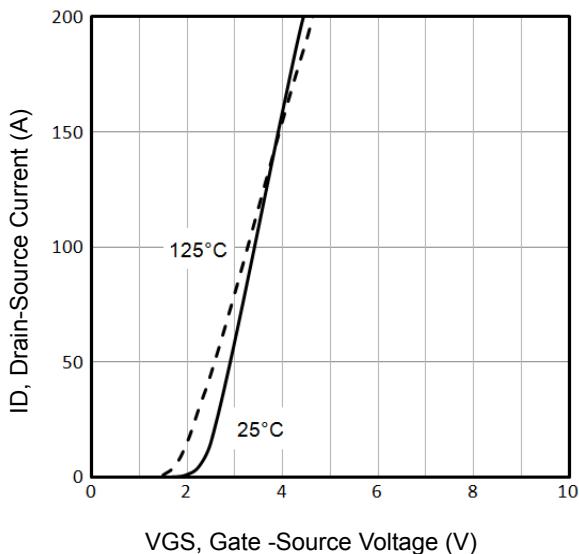


Fig3. Typical Transfer Characteristics

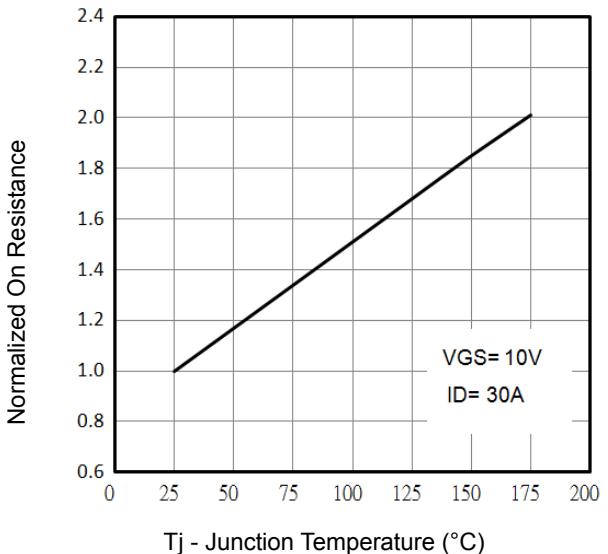


Fig4. Normalized On-Resistance Vs. T_j

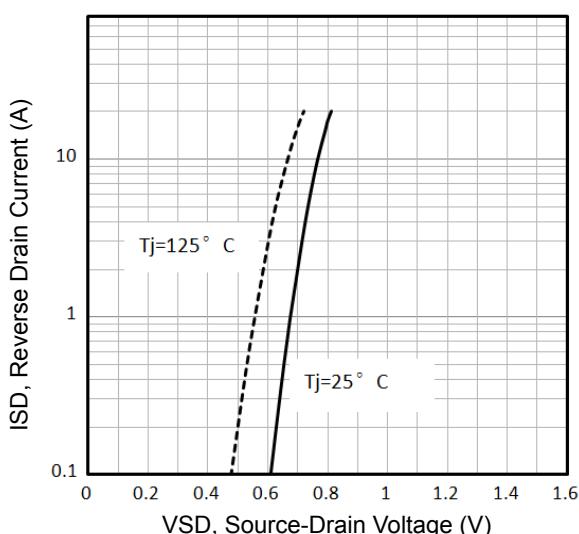


Fig5. Typical Source-Drain Diode Forward Voltage

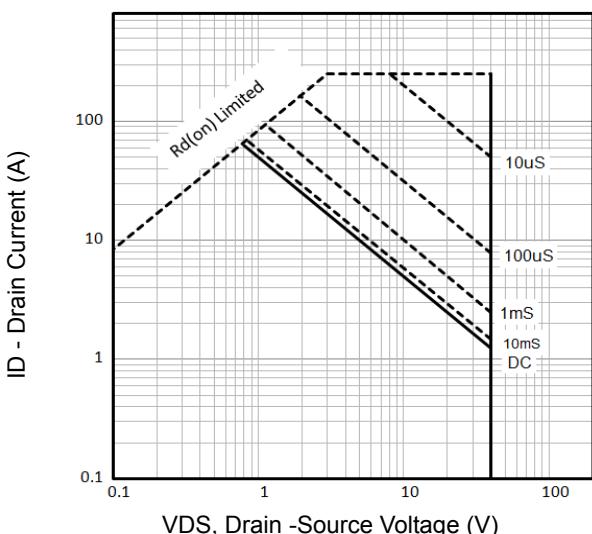


Fig6. Maximum Safe Operating Area



Typical Characteristics

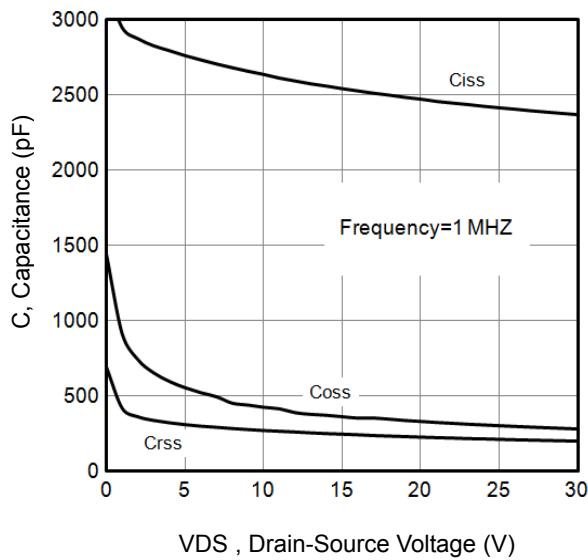


Fig7. Typical Capacitance Vs.Drain-Source Voltage

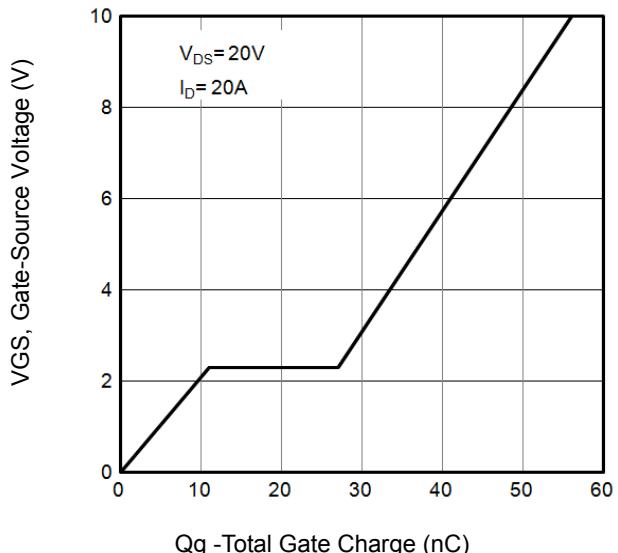


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

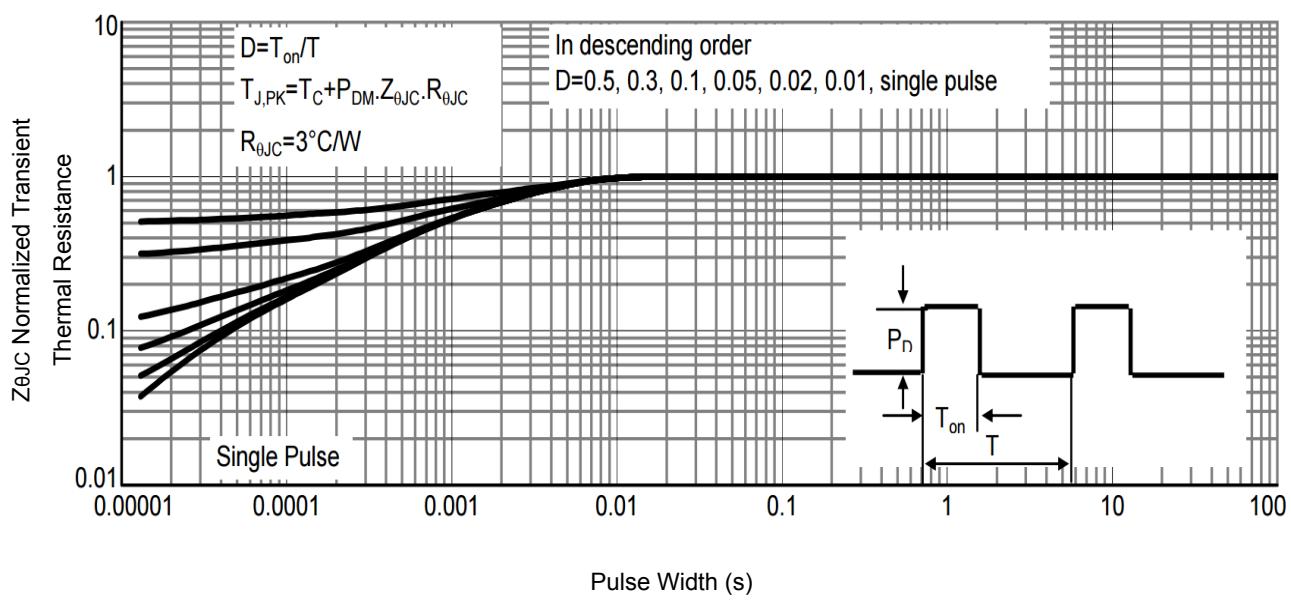


Fig9 . Normalized Maximum Transient Thermal Impedance

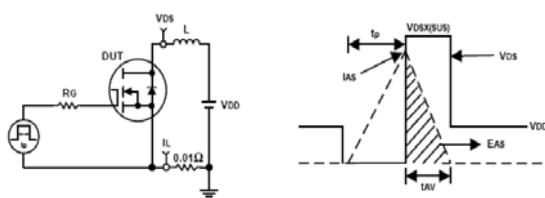


Fig10. Unclamped Inductive Test Circuit and waveforms

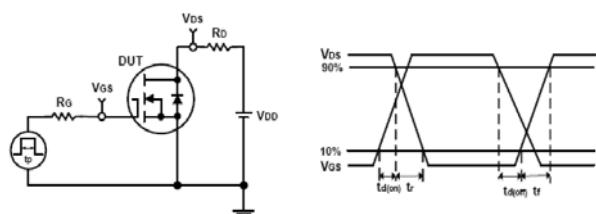
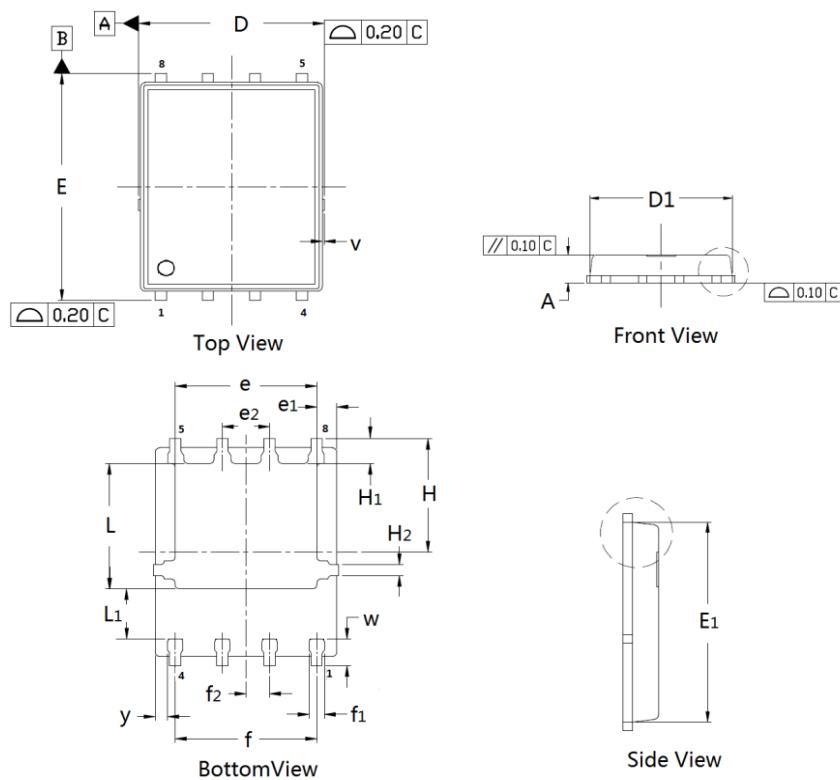


Fig11. Switching Time Test Circuit and waveforms



PDFN5×6 Package Outline Data



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.02	1.10	D	4.90	4.98	5.10
D ₁	4.80	4.89	5.00	E	6.00	6.11	6.20
E ₁	5.65	5.74	5.85	e	3.72	3.80	3.92
e ₁	--	0.54	--	e ₂	--	1.27	--
f	--	3.82	--	f ₁	0.31	0.37	0.51
f ₂	--	0.64	--	H	--	3.15	--
H ₁	0.59	0.63	0.79	H ₂	0.26	0.28	0.32
L	3.38	3.45	3.58	L ₁	--	1.39	--
v	--	0.13	--	w	0.64	0.68	0.84
y	--	0.34	--		--	--	--

Customer Service

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